

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	169	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump\$3)) flipchip (flip adj chip)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier) underfill\$4 (under adj fill\$4)) same (polyimide passivat\$6)	US-PGPUB; USPAT	OR	ON	2005/01/12 11:33
L16	5711	438/108.ccls. 438/118.ccls. 438/126.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/132.ccls. 438/601.ccls. 438/958.ccls.	US-PGPUB; USPAT	OR	OFF	2005/01/12 09:00
L17	16	(438/108.ccls. 438/118.ccls. 438/126.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/958.ccls.) and (438/132.ccls. 438/601.ccls.)	US-PGPUB; USPAT	OR	OFF	2005/01/12 09:22
L18	41	((chip die dice (integrated adj circuit) ic) with pad) same (solder near (ball bump\$3)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier) (flip adj chip) flipchip) same (polyimide passivat\$6) same (underfill\$4 (under adj fill\$4))	US-PGPUB; USPAT	OR	ON	2005/01/12 09:48
L19	15	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump\$3)) flipchip (flip adj chip)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier)) same (polyimide passivat\$6) same (underfill\$4 (under adj fill\$4))	US-PGPUB; USPAT	OR	ON	2005/01/12 10:39
L20	3069	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump\$3)) flipchip (flip adj chip)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier) polyimide passivat\$6 underfill\$4 (under adj fill\$4))	US-PGPUB; USPAT	OR	ON	2005/01/12 09:14
L21	706	16 and 20	US-PGPUB; USPAT	OR	ON	2005/01/12 09:06
L22	32	21 and fuse	US-PGPUB; USPAT	OR	ON	2005/01/12 10:45

L23	478	((solder near (ball bump\$3)) flipchip (flip adj chip)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier) underfill\$4 (under adj fill\$4)) same (polyimide passivat\$6)	US-PGPUB; USPAT	OR	ON	2005/01/12 09:09
L24	122	16 and 23	US-PGPUB; USPAT	OR	ON	2005/01/12 13:03
L25	277	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump\$3)) flipchip (flip adj chip)) same (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier)) same (polyimide passivat\$6 fuse underfill\$4 (under adj fill\$4))	US-PGPUB; USPAT	OR	ON	2005/01/12 09:12
L26	84	16 and 25	US-PGPUB; USPAT	OR	ON	2005/01/12 15:02
L28	710	((chip die dice (integrated adj circuit) ic) with pad) and ((solder near (ball bump\$3)) flipchip (flip adj chip)) and (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier) polyimide passivat\$6 fuse underfill\$4 (under adj fill\$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:16
L29	46	((chip die dice (integrated adj circuit) ic) with pad) and ((solder near (ball bump\$3)) flipchip (flip adj chip)) and (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier)) and (polyimide passivat\$6 fuse underfill\$4 (under adj fill\$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:05
L30	152	(chip die dice (integrated adj circuit) ic pad) and ((solder near (ball bump\$3)) flipchip (flip adj chip)) and (((packag\$4 wir\$4 assembly) near substrate) (chip adj carrier)) and (polyimide passivat\$6 fuse underfill\$4 (under adj fill\$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 15:15
L31	1	"6121689".pn.	US-PGPUB; USPAT	OR	ON	2005/01/12 15:04
L32	1	jp-11340270-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/01/12 16:07
L33	1	"6028011".pn.	US-PGPUB; USPAT	OR	OFF	2005/01/12 16:07

L34	13	("5462638" "5773359").PN. OR ("6028011").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/12 16:07
S1	5	jp-2000357743-\$.did. jp-2002203866-\$.did. 2003jp-0144390.ap,prai.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/12 08:30